

Product / Package Information

Package	LQFP
Lead Count	64
Body Size	10 X 10 X 1.4
Terminal Finish	100 Sn
MS Number	MS010643B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.20 E-01	86.91	869100	62.20	621956
Thermosets	Epoxy and Phenol resin	Proprietary	3.24 E-02	12.78	127800	9.15	91458
Other inorganic materials	Carbon black	1333-86-4	7.86 E-04	0.31	3100	0.22	2218
Subtotal			2.54 E-01	100	1000000	71.56	715632

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.14 E-02	97.50	962028	20.16	201602
Copper & its alloys	Iron	7439-89-6	2.23 E-03	2.35	29994	0.63	6286
Copper & its alloys	Zinc	7440-66-6	4.80 E-04	0.12	6463	0.14	1354
Copper & its alloys	Phosphorus	7723-14-0	1.13 E-04	0.03	1515	0.03	317
Subtotal			7.43 E-02	100.00	1000000	20.96	209560

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.35 E-04	100	1000000	0.21	2074

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.11 E-03	100	1000000	1.44	14416

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	1.13 E-03	99	990000	0.32	3196
Precious Metals	Palladium	7440-05-3	1.14 E-05	1	10000	0.003	32
Subtotal			1.14 E-03	100	1000000	0.32	3228

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.62 E-02	100	1000000	4.56	45589

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.48 E-03	73.54	735400	0.70	6987
Other organic materials	Epoxy resin A	TS ref# 10013	2.47 E-04	7.35	73500	0.07	698
Others	Anhydride	TS ref# 10181	2.47 E-04	7.35	73500	0.07	698
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	9.90 E-05	2.94	29400	0.03	279
Other organic materials	Epoxy resin B	TS ref# 10237	9.90 E-05	2.94	29400	0.03	279
Others	Epoxy resin modifier	TS ref# 10038	9.90 E-05	2.94	29400	0.03	279
Others	Anhydride	TS ref# 10180	9.90 E-05	2.94	29400	0.03	279
Subtotal			3.37 E-03	100.00	1000000	0.95	9501

Package Totals			Weight (g) 3.54 E-01			Percentage (%) 100.00	PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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